

ABSTRACT**APPARATUS AND METHOD FOR
PICK AND PLACE HANDLING**

5

This invention relates to a method and apparatus for pick and place handling of electronic components that have been formed on a common substrate and then separated on a cutting chuck. A transferring means is provided formed with openings for receiving
10 separated components. The opening is defined by walls of which at least one is movable so as to engage the components and hold them in a fixed configuration and orientation while they are moved by a sliding motion through a processing unit and onto a transfer platform for delivery to an output track.

FIG. 1a